



WW25Q

±1%, ±5%

Metal low ohm power chip resistors Size 2512 (6432), 1W RoHS Exemption free and Lead free products Halogen free Sensing Type

*Contents in this sheet are subject to change without prior notice.



FEATURE

- 1. Ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS exemption free and Lead free product
- 6. Excellent Heat dissipation and inrush withstand

APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

DESCRIPTION

The resistors are constructed in a high grade low resistive metal body. The structure applies no trimming configuration to provide excellent heat dissipation and inrush withstand capability. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead free terminations.



Fig 1. Construction of Chip-R

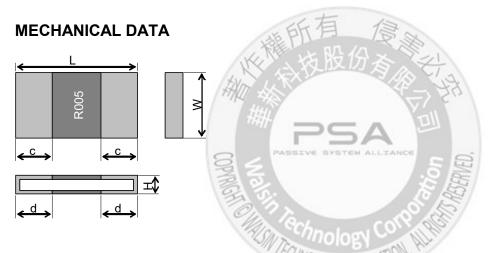
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QUICK REFERENCE DATA

Item	General Specification
Series No.	WW25Q
Size code	2512 (6432)
Resistance Tolerance	±5% , ±1%
Resistance Range	2mΩ ~ 10mΩ, 12mΩ, 15mΩ
TCR (ppm/°C)	±100 ppm/°C
Max. power at T _{amb} =70°C	1 W
Max. Operation Current (DC or RMS)	22.3A ~ 8.1A
Climatic category (IEC 60068)	55/155/56

Note : Max. Operation Current : So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$ listed above.



Туре	Size(inch)	Resistance	L(mm)	W(mm)	H(mm)	c(mm)	d(mm)
		2mΩ			0.38±0.15	1.1±	0.25
		3mΩ			0.45±0.15	2.2±	0.25
		4mΩ			0.35±0.15	2.2±	0.25
		5mΩ			0.34±0.15	1.95	:0.25
		6mΩ			0.34±0.15	1.75	:0.25
WW25Q	2512	7mΩ	6.3±0.25	3.1±0.25	0.35±0.15	1.4±	0.25
		8mΩ			0.35±0.15	1.1±	0.25
		9mΩ			0.35±0.15	0.8±	0.25
		10mΩ			0.23±0.15	1.75	:0.25
		12mΩ			0.23±0.15	1.4±	0.25
		15mΩ			0.23±0.15	0.95	0.25

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MARKING

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

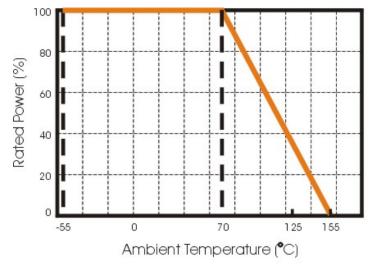
Example:

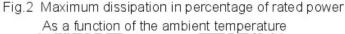
 $R005 = 0.005\Omega$ $R010 = 0.010\Omega$

FUNCTIONAL DESCRIPTION

Derating curve

The power that the resistor can dissipate depends on the operating temperature; see Fig.2





MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chnology

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



SOLDERING CONDITIONS

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig

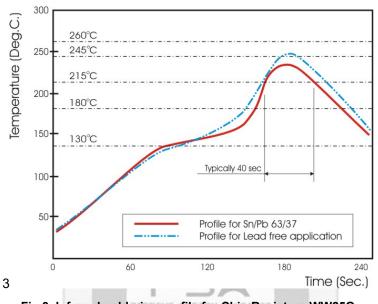


Fig 3. Infrared soldering profile for Chip Resistors WW25Q

CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

WW25	Q	R005	J	т	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WW25 : 2512	Q:1W	R is first digit followed by 3 significant digits. $0.010\Omega = R010$ $0.005\Omega = R005$	J :±5% F :±1%	T :7" reeled in tape	L = Sn base (lead free)

Reeled tape packaging : 12mm width embossed taping 4,000pcs per reel.



TEST & REQUIREMENTS (JIS C 5201-1 : 1998)

No.	Test items	Table- 4(1) Condition of test (JIS C 5201-1)	Performance requirements
1	Visual examination	Sub–clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, as checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this specification.
	Resistance	Resistance value shall be measured by mounting the substrate of the following condition. Current Current terminal Corper clad Voltage terminal Corper clad Voltage terminal Solder resist a: 3mm (1m Ω), 2.6mm (5m Ω), 1.8mm (10m Ω , 15m Ω) Thickness of copper clad: 0.035mm 4-Terminal method Measurement current: 1(A)	As in 4.5.2 The resistance value shall correspond with the rated resistance taking into account the specified tolerance.
		Note: The measuring apparatus corresponding to DC Low-ohm Mater (1A) of AX-1152D for ADEX CORPORATION.	
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4(See Figure–5) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s±5 s Insulation resistance	No breakdown or flash over
		Test voltage: Insulation voltage Duration: 1 min.	R≥1GΩ
4	Solderability	Sub-clause 4.17 Without aging Flux: The resistors shall be immersed in a non-activated soldering flux for 2 s. Bath temperature: 235 °C±5 °C Immersion time: 2 s±0.5 s	As in 4.17.4.5 The terminations shall be covered with a smooth and bright solder coating.
5	Mounting Overload (in the mounted state)	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.13 The applied voltage shall be 2.5 times the rated voltage or the current corresponding to. Duration: 2 s	
	Solvent resistance of the marking	Visual examination Resistance Sub–clause 4.30 Solvent: 2–propanol Solvent temperature: 23 °C±5 °C Method 1 Rubbing material: cotton wool Without recovery	No visible damage ∆ R ≤ ±1% Legible marking

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		Table-4(2)	99.
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub–clause 4.31	
		Substrate material: Epoxide woven glass	
	25 10 10 10 10 10 10 10 10 10 10 10 10 10	Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 1 mm	
		Resistance	∆R≤±1%
	Final measurements	Sub–clause 4.33.6	
		Visual examination	No visible damage
7	Resistance to soldering heat	Sub–clause 4.18	
		Solder temperature: 260 °C±5 °C	
		Immersion time: 10 s±0.5 s	an be management
		Visual examination	As in 4.18.3.4
			No sign of damage such as cracks.
		New Soundards and	∆R≤±1%
	Component solvent	Resistance	
	resistance	Sub–clause 4.29	
		Solvent: 2–propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 2	
		Recovery: 48 h	No visible damage
		Visual examination	∆R≤±1%
		Resistance	
8	Mounting	Sub–clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	Adhesion	Sub-clause 4.32	
		Force: 5 N	
		Duration: 10 s±1 s	
	B 21 F 2	Visual examination	No visible damage
	Rapid change temperature	Sub–clause 4.19	
		Lower category temperature:-55 °C	
		Upper category temperature:+155 °C	
		Duration of exposure at each temperature: 30	
		min.	
		Number of cycles: 5 cycles.	Ne visible demose
		Visual examination	No visible damage ∆ R ≤ ±1%
		Resistance	$\Delta R \ge \pm 170$

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	Table-4(3)						
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements				
9	Climatic sequence –Dry heat	Sub-clause 4.23 Sub-clause 4.23.2 Test temperature: +155 °C Duration: 16 h					
	–Damp heat, cycle (12+12hour cycle) First cycle –Cold	Sub-clause 4.23.3 Test method: 2 Test temperature: 55 °C [Severity(2)] Sub-clause 4.23.4					
	–Damp heat, cycle (12+12hour cycle) Remaining cycle –D.C. load	Test temperature –55 °C Duration: 2h Sub–clause 4.23.6 Test method: 2 Test temperature: 55 °C [Severity (2)] Number of cycles: 5 cycles Sub–clause 4.23.7 The applied current shall be the rated current. Duration: 1 min. Visual examination Resistance	No visible damage ∆ R ≤ ±5 %				
10	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Endurance at 70 °C	Sub-clause 4.25.1 Ambient temperature: 70 °C±2 °C Duration: 1000 h The current shall be applied in cycles of 1.5 h on and 0.5 h. The applied current shall be the rated current Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage ∆ R ≤ ±5 %				

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		Table-4(4)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
11	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Variation of resistance with temperature	Sub–clause 4.8 +20 °C / +155 °C	As in Table–1
12	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Damp heat, steady state	Sub–clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ±3 % Without current applied. Visual examination Resistance	No visible damage Legible marking ∆ R ≤ ±5%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–4
	Mounting	Sub–clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Endurance at upper category temperature	Sub–clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage ∆ R ≤ ±5%



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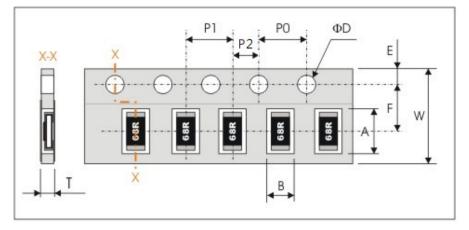
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PACKAGING

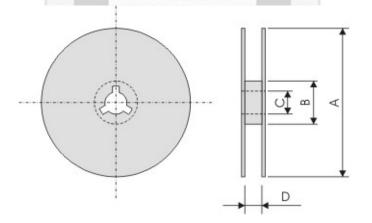
Plastic Tape specifications (unit :mm)



Symbol	А	В	W	F	E
Dimensions	6.75±0.20	3.50±0.20	12.00±0.30	5.50±0.10	1.75±0.10
	•	1CA	17		

ALE PIT A						
Symbol	P1	P0	P2	ΦD	Т	
Dimensions	4.00±0.10	4.00±0.10	2.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	0.90±0.20	

Reel dimensions



Symbol	А	В	С	D
(unit : mm)	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	13.0±1.0

Taping quantity

- Chip resistors 4,000 pcs per reel.

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